

NodeMCU Lua Lolin V3 Modul mit ESP8266 12E Datenblatt



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1. Features

- 802.11 b/g/n
- Integrated low power 32-bit MCU
- Integrated 10-bit ADC
- Integrated TCP/IP protocol stack
- Integrated TR switch, balun, LNA, power amplifier and matching network
- Integrated PLL, regulators, and power management units
- Supports antenna diversity
- Wi-Fi 2.4 GHz, support WPA/WPA2
- Support STA/AP/STA+AP operation modes
- Support Smart Link Function for both Android and iOS devices
- SDIO 2.0, (H) SPI, UART, I2C, I2S, IRDA, PWM, GPIO
- STBC, 1x1 MIMO, 2x1 MIMO
- A-MPDU & A-MSDU aggregation and 0.4s guard interval
- Deep sleep power <10uA, Power down leakage current < 5uA
- Wake up and transmit packets in < 2ms
- Standby power consumption of < 1.0mW (DTIM3)
- +20dBm output power in 802.11b mode
- Operating temperature range -40C ~ 125C

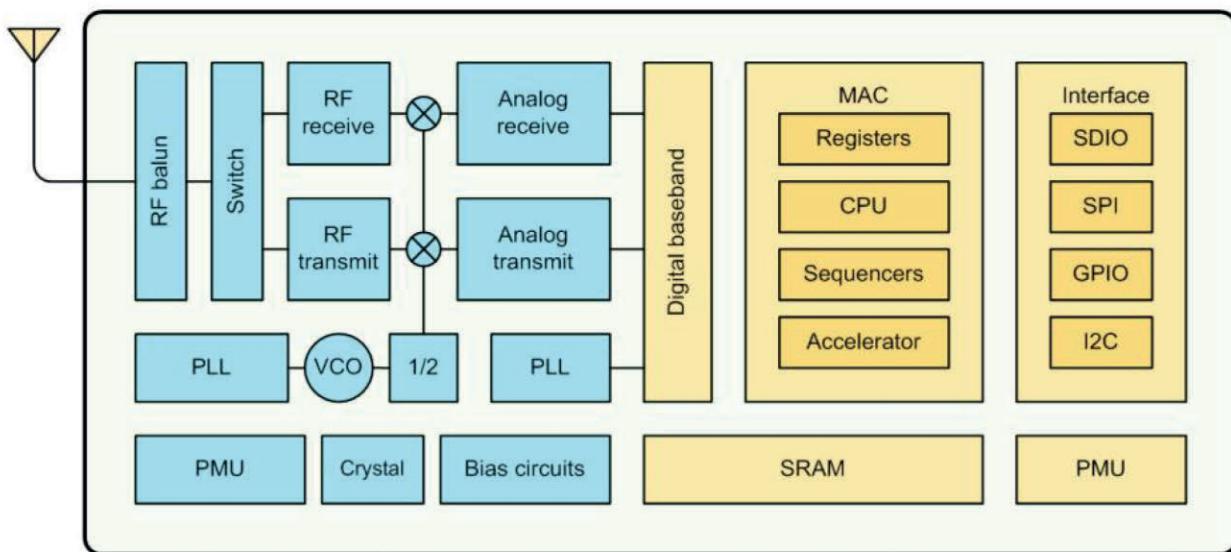


Figure 1 ESP8266EX Block Diagram

The module supports standard IEEE802.11 b/g/n agreement, complete TCP/IP protocol stack. Users can use the add modules to an existing device networking, or building a separate network controller.

ESP8266 is high integration wireless SOCs, designed for space and power constrained mobile platform designers.

It provides unsurpassed ability to embed Wi-Fi capabilities within other systems, or to function as a standalone application, with the lowest cost, and minimal space requirement.

ESP8266EX offers a complete and self-contained Wi-Fi networking solution; it can be used to host the application or to offload Wi-Fi networking functions from another application processor.

When ESP8266EX hosts the application, it boots up directly from an external flash. It has integrated cache to improve the performance of the system in such applications.

Alternately, serving as a Wi-Fi adapter, wireless internet access can be added to any micro controllerbased design with simple connectivity (SPI/SDIO or I2C/UART interface).

ESP8266EX is among the most integrated WiFi chip in the industry; it integrates the antenna switches, RF balun, power amplifier, low noise receive amplifier, filters, power management modules, it requires minimal external circuitry, and the entire solution, including front-end module, is designed to occupy minimal PCB area.

ESP8266EX also integrates an enhanced version of Tensilica's L106 Diamond series 32-bit processor, with on-chip SRAM, besides the Wi-Fi functionalities. ESP8266EX is often integrated with external sensors and other application specific devices through its GPIOs; codes for such applications are provided in examples in the SDK.

2. Parameters

Table 1 below describes the major parameters.

Table 1 - Parameters

| Categories | Items | Values |
|---------------------|-----------------------------|--|
| WiFi Paramters | WiFi Protocols | 802.11 b/g/n |
| | Frequency Range | 2.4GHz-2.5GHz (2400M-2483.5M) |
| Hardware Parameters | Peripheral Bus | UART/HSPI/I2C/I2S/Ir Remote Control |
| | | GPIO/PWM |
| | Operating Voltage | 3.0~3.6V |
| | Operating Current | Average value: 80mA |
| | Operating Temperature Range | -40°~125° |
| | Ambient Temperature Range | Normal temperature |
| | Package Size | 16mm*24mm*3mm |
| | External Interface | N/A |
| | Wi-Fi mode | station/softAP/SoftAP+station |
| Software Parameters | Security | WPA/WPA2 |
| | Encryption | WEP/TKIP/AES |
| | Firmware Upgrade | UART Download / OTA (via network) / download and write firmware via host |
| | Software Development | Supports Cloud Server Development / SDK for custom firmware development |
| | Network Protocols | IPv4, TCP/UDP/HTTP/FTP |
| | User Configuration | AT Instruction Set, Cloud Server, Android/iOS App |

3. Pin Descriptions

There are altogether 22 pin counts, the definitions of which are described in Figure 2 below

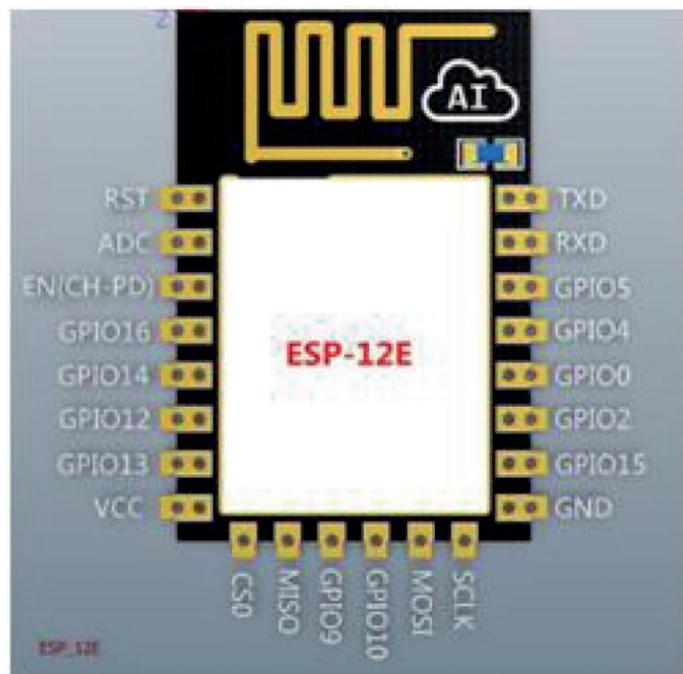


Figure 2 - ESP-12E Pin design

Table 2 - Pin Descriptions

| NO. | Pin Name | Function |
|-----|----------|--|
| 1 | RST | Reset the module |
| 2 | ADC | A/D Conversion result. Input voltage range 0-1v, scope: 0-1024 |
| 3 | EN | Chip enable pin. Active high |
| 4 | IO16 | GPIO16; can be used to wake up the chipset from deep sleep mode. |
| 5 | IO14 | GPIO14; HSPI_CLK |
| 6 | IO12 | GPIO12; HSPI_MISO |
| 7 | IO13 | GPIO13; HSPI_MOSI; UART0_CTS |
| 8 | VCC | 3.3V power supply (VDD) |
| 9 | CS0 | Chip selection |
| 10 | MISO | Slave output Main input |

Table 2 - Pin Descriptions...Continued

| | | |
|----|------|---------------------------------|
| 11 | IO9 | GPIO9 |
| 12 | IO10 | GPIO10 |
| 13 | MOSI | Main output slave input |
| 14 | SCLK | Clock |
| 15 | GND | GND |
| 16 | IO15 | GPIO15; MTDO; HSPICS; UART0_RTS |
| 17 | IO2 | GPIO2; UART1_RXD |
| 18 | IO0 | GPIO0 |
| 19 | IO4 | GPIO4 |
| 20 | IO5 | GPIO5 |
| 21 | RXD | UART0_RXD; GPIO3 |
| 22 | TXD | UART0_TXD; GPIO1 |

Table 3 - Pin Mode

| Mode | GPIO15 | GPIO0 | GPIO2 |
|------------|--------|-------|-------|
| UART | Low | Low | High |
| Flash Boot | Low | High | High |

Table 4 - Receiver Sensitivity

| Parameters | Min | Typical | Max | Unit |
|-----------------------------------|------|---------|------|----------|
| Input frequency | 2412 | | 2484 | MHz |
| Input impedance | | 50 | | Ω |
| Input reflection | | | -10 | dB |
| Output power of PA for 72.2Mbps | 15.5 | 16.5 | 17.5 | dBm |
| Output power of PA for 11b mode | 19.5 | 20.5 | 21.5 | dBm |
| Sensitivity | | | | |
| DSSS, 1Mbps | | -98 | | dBm |
| CCK, 11Mbps | | -91 | | dBm |
| 6Mbps (1/2 BPSK) | | -93 | | dBm |
| 54Mbps (3/4 64-QAM) | | -75 | | dBm |
| HT20, MCS7 (65Mbps, 72.2Mbps) | | -72 | | dBm |
| Adjacent Channel Rejection | | | | |
| OFDM, 6Mbps | 37 | | | dB |
| OFDM, 54Mbps | 21 | | | dB |
| HT20, MCS0 | 37 | | | dB |
| HT20, MCS7 | 20 | | | dB |

4. Packaging and Dimension

The external size of the module is 16mm*24mm*3mm, as is illustrated in Figure 3 below.

The type of flash integrated in this module is an SPI flash, the capacity of which is 4 MB, and the package size of which is SOP-210mil. The antenna applied on this module is a 3DBi PCB-on-board antenna.



Figure 3 - [Module Pin Counts, 22 pin, 16 mm *24 mm *3 mm]

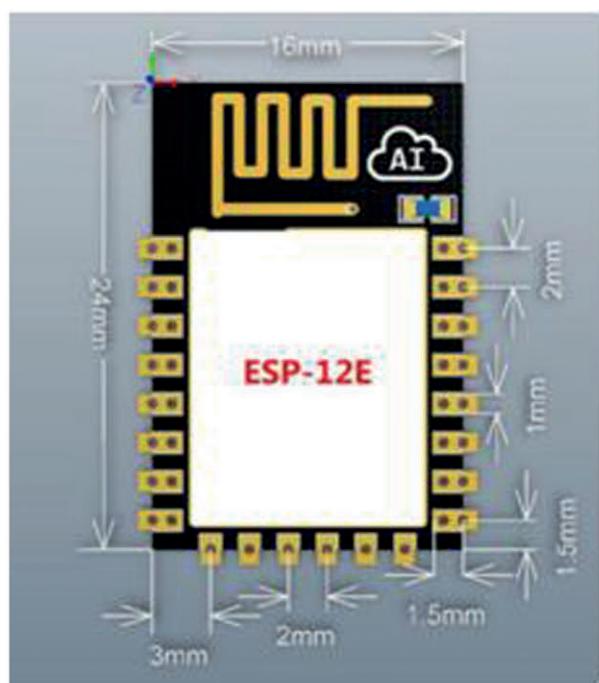


Figure 4 - Top View of ESP-12E WiFi Module

Table 5 - Dimension of ESP-12E WiFi Modul

| Length | Width | Height | PAD Size(Bottom) | Pin Pitch |
|--------|-------|--------|------------------|-----------|
| 16 mm | 24mm | 3 mm | 0.9 mm x 1.7 mm | 2mm |

5. Functional Descriptions

5.1. MCU

ESP8266EX is embedded with Tensilica L106 32-bit micro controller (MCU), which features extra low power consumption and 16-bit RSIC. The CPU clock speed is 80MHz. It can also reach a maximum value of 160MHz.

ESP8266EX is often integrated with external sensors and other specific devices through its GPIOs; codes for such applications are provided in examples in the SDK.

5.2. Memory Organization

5.2.1. Internal SRAM and ROM

ESP8266EX WiFi SoC is embedded with memory controller, including SRAM and ROM. MCU can visit the memory units through iBus, dBus, and AHB interfaces. All memory units can be visited upon request, while a memory arbiter will decide the running sequence according to the time when these requests are received by the processor.

According to our current version of SDK provided, SRAM space that is available to users is assigned as below:

- RAM size < 36kB, that is to say, when ESP8266EX is working under the station mode and is connected to the router, programmable space accessible to user in heap and data section is around 36kB.)
- There is no programmable ROM in the SoC, therefore, user program must be stored in an external SPI flash.

5.2.2. External SPI Flash

This module is mounted with an 4 MB external SPI flash to store user programs. If larger definable storage space is required, a SPI flash with larger memory size is preferred.

Theoretically speaking, up to 16 MB memory capacity can be supported.

Suggested SPI Flash memory capacity:

- OTA is disabled: the minimum flash memory that can be supported is 512 kB;
- OTA is enabled: the minimum flash memory that can be supported is 1 MB.

Several SPI modes can be supported, including Standard SPI, Dual SPI, and Quad SPI.

Therefore, please choose the correct SPI mode when you are downloading into the flash, otherwise firmwares/programs that you downloaded may not work in the right way.

5.3. Crystal

Currently, the frequency of crystal oscillators supported include 40MHz, 26MHz and 24MHz.

The accuracy of crystal oscillators applied should be $\pm 10\text{PPM}$, and the operating temperature range should be between -20°C and 85°C.

When using the downloading tools, please remember to select the right crystal oscillator type. In circuit design, capacitors C1 and C2, which are connected to the earth, are added to the input and output terminals of the crystal oscillator respectively. The values of the two capacitors can be flexible, ranging from 6pF to 22pF, however, the specific capacitive values of C1 and C2 depend on further testing and adjustment on the overall performance of the whole circuit. Normally, the capacitive values of C1 and C2 are within 10pF if the crystal oscillator frequency is 26MHz, while the values of C1 and C2 are 10pF<C1, C2<22pF if the crystal oscillator frequency is 40MHz.

5.4. Interfaces

Table 6 Descriptions of Interfaces

| Interface | Pin Name | Description |
|-------------------|---|---|
| HSPI | IO12(MISO) IO13(MOSI) IO14(CLK) IO15(CS) | SPI Flash 2, display screen, and MCU can be connected using HSPI interface. |
| PWM | IO12(R) IO15(G) IO13(B) | Currently the PWM interface has four channels, but users can extend the channels according to their own needs. PWM interface can be used to control LED lights, buzzers, relays, electronic machines, and so on. |
| IR Remote Control | IO14(IR_T) IO5(IR_R) | The functionality of Infrared remote control interface can be implemented via software programming. NEC coding, modulation, and demodulation are used by this interface. The frequency of modulated carrier signal is 38KHz. |
| ADC | TOUT | ESP8266EX integrates a 10-bit analog ADC. It can be used to test the power-supply voltage of VDD3P3 (Pin3 and Pin4) and the input power voltage of TOUT (Pin 6). However, these two functions cannot be used simultaneously. This interface is typically used in sensor products. |
| I2C | IO14(SCL) IO2(SDA) | I2C interface can be used to connect external sensor products and display screens, etc. |

Table 6 Descriptions of Interfaces...Continued

| Interface | Pin Name | Description |
|-----------|---|--|
| UART | UART0: TXD (U0TXD) RXD (U0RXD) IO15 (RTS) IO13 (CTS) UART1: IO2(TXD) | Devices with UART interfaces can be connected with the module. Downloading: U0TXD+U0RXD or GPIO2+U0RXD Communicating: UART0: U0TXD, U0RXD, MTDO (U0RTS), MTCK (U0CTS) Debugging: UART1_TXD (GPIO2) can be used to print debugging information. By default, UART0 will output some printed information when the device is powered on and is booting up. If this issue exerts influence on some specific applications, users can exchange the inner pins of UART when initializing, that is to say, exchange U0TXD, U0RXD with U0RTS, U0CTS. |
| I2S | I2S Input: IO12 (I2SI_DATA); IO13 (I2SI_BCK); I2S Output: IO14 (I2SI_WS); I2S Output: IO15 (I2SO_BCK); IO3 (I2SO_DATA); IO2 (I2SO_WS). | I2S interface is mainly used for collecting, processing, and transmission of audio data. |

5.5. Absolute Maximum Ratings

Table 8 Recommended Operating Conditions

| Rating | Condition | Value | Unit |
|-------------------------------|---------------------|--------------|------|
| Storage Temperature | | -40 to 125 | °C |
| Maximum Soldering Temperature | | 260 | °C |
| Supply Voltage | IPC/JEDEC J-STD-020 | +3.0 to +3.6 | V |

5.7. Digital Terminal Characteristics

Table 9 Digital Terminal Characteristics

| Operating Condition | Symbol | Min | Typ | Max | Unit |
|-----------------------|--------|-----|-----|-----|------|
| Operating Temperature | | -40 | 20 | 125 | °C |
| Supply voltage | VDD | 3.0 | 3.3 | 3.6 | V |

Note: Test conditions: $V_{DD} = 3.3V$, Temperature = 20 °C, if nothing special is stated.

6. RF Performance

Table 10 RF Performance

| Description | Min. | Typ. | Max | Unit |
|-----------------------------------|------|------|--------|------|
| Input frequency | 2400 | | 2483.5 | MHz |
| Input impedance | | 50 | | ohm |
| Input reflection | | | -10 | dB |
| Output power of PA for 72.2Mbps | 15.5 | 16.5 | 17.5 | dBm |
| Output power of PA for 11b mode | 19.5 | 20.5 | 21.5 | dBm |
| Sensitivity | | | | |
| CCK, 1Mbps | | -98 | | dBm |
| CCK, 11Mbps | | -91 | | dBm |
| 6Mbps (1/2 BPSK) | | -93 | | dBm |
| 54Mbps (3/4 64-QAM) | | -75 | | dBm |
| HT20, MCS7 (65Mbps, 72.2Mbps) | | -72 | | dBm |
| Adjacent Channel Rejection | | | | |
| OFDM, 6Mbps | | 37 | | dB |
| OFDM, 54Mbps | | 21 | | dB |
| HT20, MCS0 | | 37 | | dB |
| HT20, MCS7 | | 20 | | dB |

7. Power Consumption

Table 11 Power Consumption

| Parameters | Min | Typical | Max | Unit |
|--|-----|---------|-----|------|
| Tx 802.11b, CCK 11Mbps, P OUT = +17dBm | | 170 | | mA |
| Tx 802.11g, OFDM 54Mbps, P OUT = +15dBm | | 140 | | mA |
| Tx 802.11n, MCS7, P OUT = +13dBm | | 120 | | mA |
| Rx 802.11b, 1024 bytes packet length, -80dBm | | 50 | | mA |
| Rx 802.11g, 1024 bytes packet length, -70dBm | | 56 | | mA |
| Rx 802.11n, 1024 bytes packet length, -65dBm | | 56 | | mA |
| Modem-Sleep① | | 15 | | mA |
| Light-Sleep② | | 0.9 | | mA |
| Deep-Sleep③ | | 10 | | uA |

1. Modem-Sleep requires the CPU to be working, as in PWM or I2S applications. According to 802.11 standards (like U-APSD), it saves power to shut down the Wi-Fi Modem circuit while maintaining a Wi-Fi connection with no data transmission. E.g. in DTIM3, to maintain a sleep 300ms-wake 3ms cycle to receive AP's Beacon packages, the current is about 15mA.

2. During Light-Sleep, the CPU may be suspended in applications like Wi-Fi switch. Without data transmission, the Wi-Fi Modem circuit can be turned off and CPU suspended to save power according to the 802.11 standard (U-APSD). E.g. in DTIM3, to maintain a sleep 300ms-wake 3ms cycle to receive AP's Beacon packages, the current is about 0.9mA.

3. Deep-Sleep does not require Wi-Fi connection to be maintained. For application with long time lags between data transmission, e.g. a temperature sensor that checks the temperature every 100s, sleep 300s and waking up to connect to the AP (taking about 0.3~1s), the overall average current is less than 1mA.

8. Reflow Profile

Table 12 - Instructions

| | |
|--|---------------------------|
| T _S max to T _L (Ramp-up Rate) | 3°C/second max |
| Preheat | |
| Temperature Min.(T _S Min.) | 150°C |
| Temperature Typical.(T _S Typ.) | 175°C |
| Temperature Min.(T _S Max.) | 200°C |
| Time(T _S) | 60~180 seconds |
| Ramp-up rate (T _L to T _P) | 3°C/second max |
| Time Maintained Above: --Temperature(T _L)/Time(T _L) | 217°C/60~150 seconds |
| Peak Temperature(T _P) | 260°C max. for 10 seconds |
| Target Peak Temperature (T _P Target) | 260°C +0/-5°C |
| Time within 5°C of actual peak(t _P) | 20~40 seconds |
| T _S max to T _L (Ramp-down Rate) | 6°C/second max |
| Tune 25°C to Peak Temperature (t) | 8 minutes max |

9. Schematics

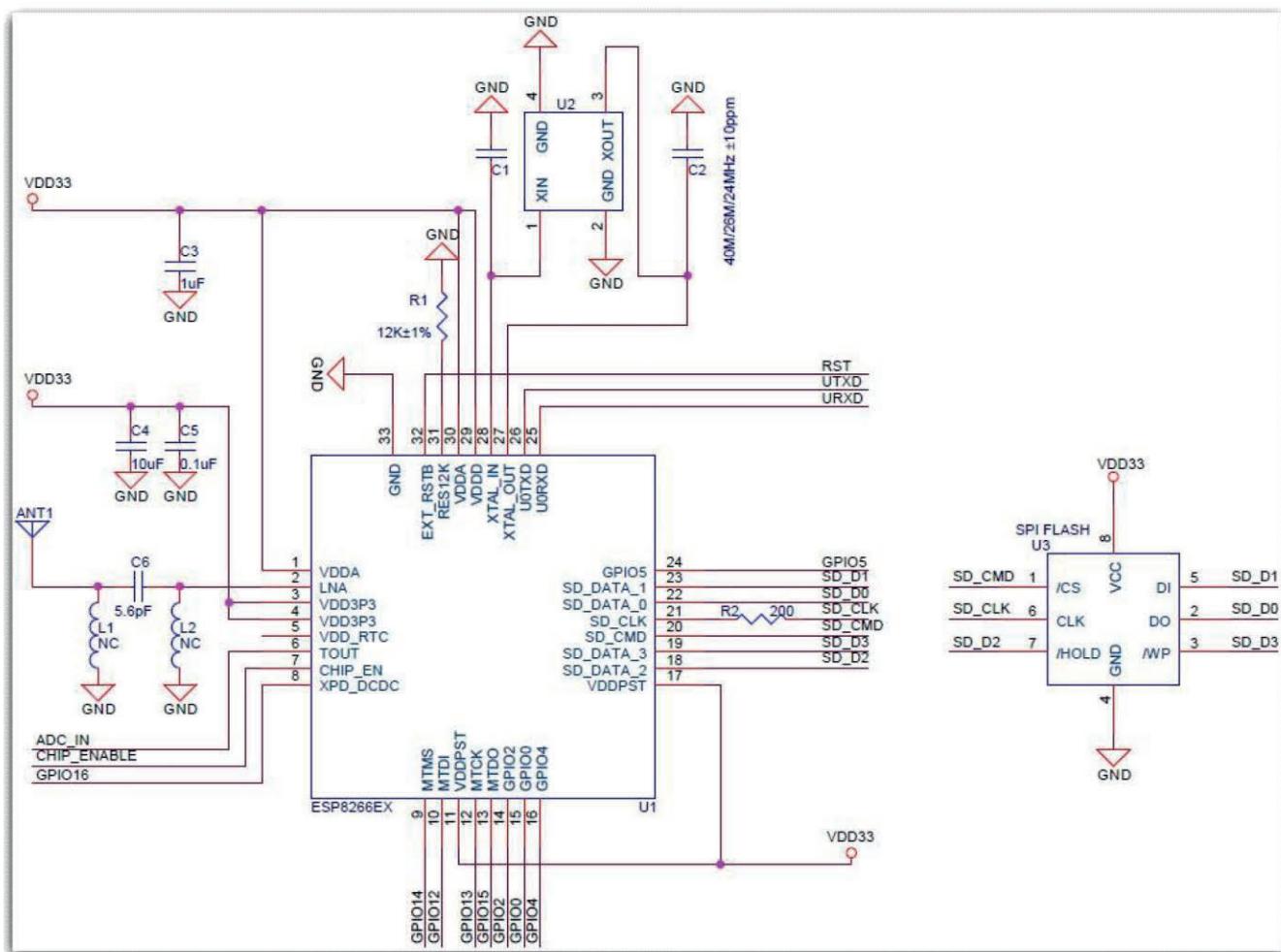


Figure 5 - Schematics of Esp-12E WiFi Module